Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **BALANCE**
2. **IN –**
3. **IN +**
4. **V –**
5. **BALANCE**
6. **OUTPUT**
7. **V +**

**.074”**

****

**.043”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential: V-**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .043” X .074” DATE: 8/17/21**

**MFG: SILICON SUPPLIES THICKNESS .014” P/N: LF157**

**DG 10.1.2**

#### Rev B, 7/1